

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUS260N10S5N019T	**Issued**	15. May 2021
MA#	MA005344501		
Package	PG-HDSOP-16-2	**Weight***	854.29 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.010	0.70	0.70	7035	7035
leadframe	inorganic material	phosphorus	7723-14-0	0.143	0.02		168	
	non noble metal	iron	7439-89-6	0.477	0.06		559	
	non noble metal	copper	7440-50-8	476.748	55.82	55.90	558066	558793
wire	non noble metal	aluminium	7429-90-5	20.819	2.44	2.44	24370	24370
encapsulation	inorganic material	zincoxide	1314-13-2	3.242	0.38		3795	
	miscellaneous	miscellaneous	-	12.970	1.52		15182	
	plastics	epoxy resin	-	48.636	5.69		56932	
	inorganic material	silicondioxide	60676-86-0	259.393	30.36	37.95	303637	379546
leadfinish	non noble metal	tin	7440-31-5	6.684	0.78	0.78	7824	7824
plating	inorganic material	phosphorus	7723-14-0	0.013			15	
	non noble metal	nickel	7440-02-0	5.316	0.62	0.62	6222	6237
solder	non noble metal	tin	7440-31-5	0.101	0.01		118	
	noble metal	silver	7440-22-4	0.126	0.01		147	
	non noble metal	lead	7439-92-1	4.799	0.56	0.58	5618	5883
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			3	
	non noble metal	iron	7439-89-6	0.009			10	
	non noble metal	copper	7440-50-8	8.798	1.03	1.03	10299	10312
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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